

**Features** 

- High isolation 2500 VRMS
- Patented coplanar structure DMC-Isolator®
- Various CTR selection available
- DC input with Transistor output
- Operating Temperature range 55 °C to 125 °C
- Leadless
- RoHS and REACH Compliance
- Halogen Free Compliance
- External creepage distance >2.8mm
- Distances through insulation >0.4mm
- Regulatory Approvals
  - ✓ UL UL1577 (E364000)
  - ✓ VDE EN60747-5-5

The CTP17 series consists of a photo transistor optically coupled to an Infrared-emitting diode in a DFN DMC-Isolator® package.

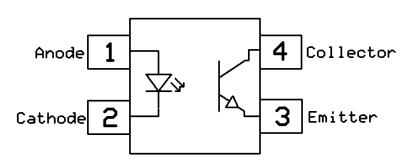
### **Applications**

- Switch mode power supplies
- Computer peripheral interface
- Microprocessor system interface

## **Description**

## **Package Outline**

## **Schematic**





## Absolute Maximum Ratings $T_A = 25^{\circ}C$ , unless otherwise specified

Stresses in excess of the absolute maximum ratings can cause permanent damage to the device. Functional operation of the device is not implied at these or any other conditions in excess of those given in the operational sections of this document. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only.

Symbol	Parameters	Ratings	Units	Notes
Viso	Isolation voltage (AC, 1 minute, 40 ~ 60% R.H.)	2500	V <sub>RMS</sub>	
Ртот	Total power dissipation	135	mW	
Topr	Operating temperature	-55 ~ +125	°C	
Tstg	Storage temperature	-55 ~ +150	°C	
Tsol	Soldering temperature	260	°C	
Emitter		•		
I <sub>F</sub>	Forward current	20	mA	
I <sub>F(TRANS)</sub>	Peak transient current (≤1µs P.W,300pps)	100	mA	
VR	Reverse voltage	6	V	
P <sub>D</sub>	Power dissipation	35	mW	
Detector		•		
Pc	Power dissipation	100	mW	
Bvceo	Collector-Emitter Breakdown Voltage	80	V	
Bveco	Emitter-Collector Breakdown Voltage	7	V	
Ic	Collector Current	50	mA	

## Electrical Characteristics $T_A = 25$ °C (unless otherwise specified)

### **Emitter Characteristics**

Symbol	Parameters	Test Conditions	Min	Тур	Max	Units	Notes
VF	Forward voltage	I <sub>F</sub> =10mA	-	1.25	1.4	V	
I <sub>R</sub>	Reverse Current	V <sub>R</sub> = 6V	-	-	5	μΑ	
Cin	Input Capacitance	f= 1MHz	-	10	30	pF	

### **Detector Characteristics**

Symbol	Parameters	Test Conditions	Min	Тур	Max	Units	Notes
B <sub>VCEO</sub>	Collector-Emitter Breakdown	Ic= 100μA	80	-	-	V	
Bveco	Emitter-Collector Breakdown	I <sub>EC</sub> = 100μA	7	-	-	V	
ICEO	Collector-Emitter Dark Current	V <sub>CE</sub> = 40V, I <sub>F</sub> =0mA	-	-	100	nA	

### **Transfer Characteristics**

Symbol	Parameters	Test Conditions		Min	Тур	Max	Units	Notes
	Current Transfer Ratio	I <sub>F</sub> = 1mA, V <sub>CE</sub> = 5V	CTP17	100		600		1
CTR			CTP17B	100	-	300	400 %	
CIK			CTP17C	200	-	400		
			CTP17D	300	-	600		
CTR	Current Transfer Ratio	I <sub>F</sub> = 1mA, V <sub>CE</sub> = 0.4V		50	-	-	%	
V	Collector-Emitter Saturation	IF= 1mA, Ic= 0.5mA		-	0.2	0.4	V	
VCE(SAT)	Voltage							
R <sub>IO</sub>	Isolation Resistance	V <sub>IO</sub> = 500V <sub>DC</sub>		5x10 <sup>10</sup>	•	-	Ω	
Cıo	Isolation Capacitance	f= 1MHz		-	0.25	1	pF	

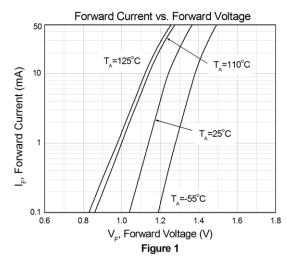
## **Switching Characteristics**

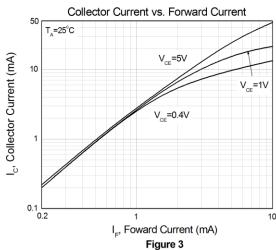
Symbol	Parameters	Test Conditions	Min	Тур	Мах	Units	Notes
tr	Rise Time		-	5	16	0	
t <sub>f</sub>	Fall Time	I <sub>C</sub> = 2mA, V <sub>CE</sub> = 2V	-	6	16	μS	
ton	Turn-on time	R <sub>L</sub> = 100Ω	-	8	20		
t <sub>off</sub>	Turn-off time		-	7	20	μS	

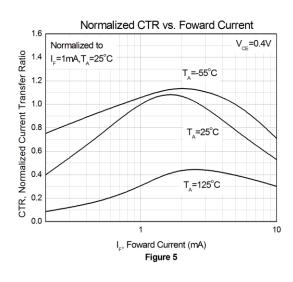
Note1:CTP17 is random shipment

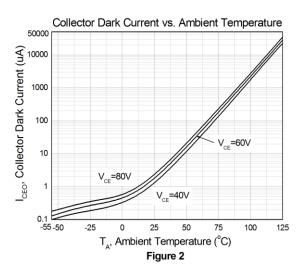


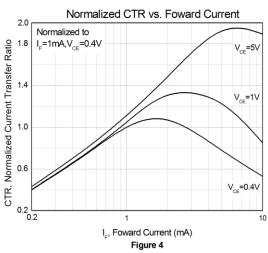
## Typical Characteristic Curves $T_A = 25$ °C, unless otherwise specified

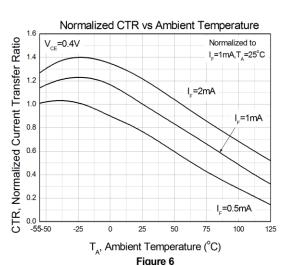






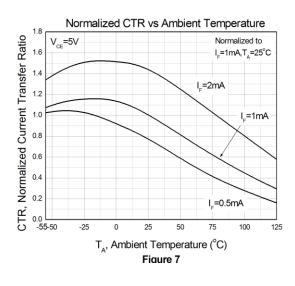


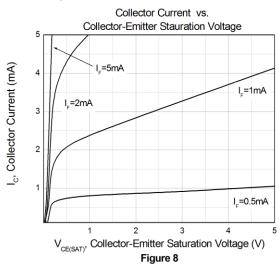


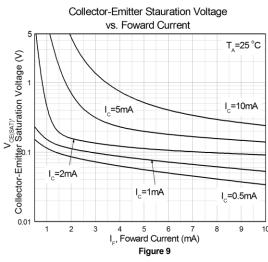


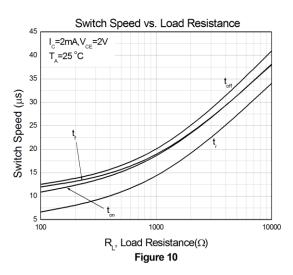


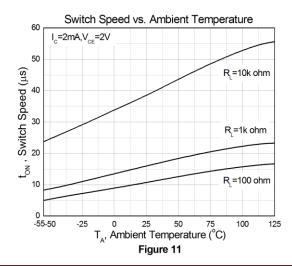
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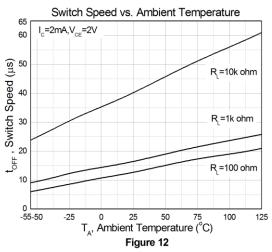




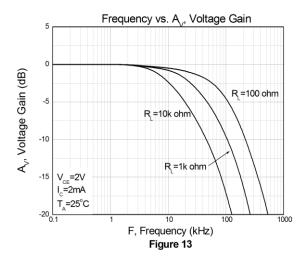




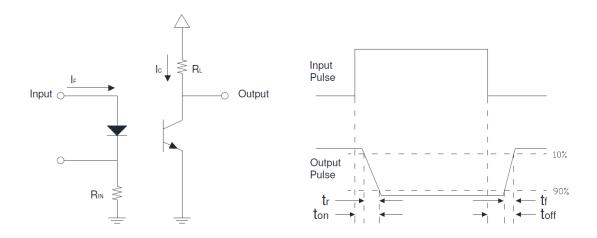




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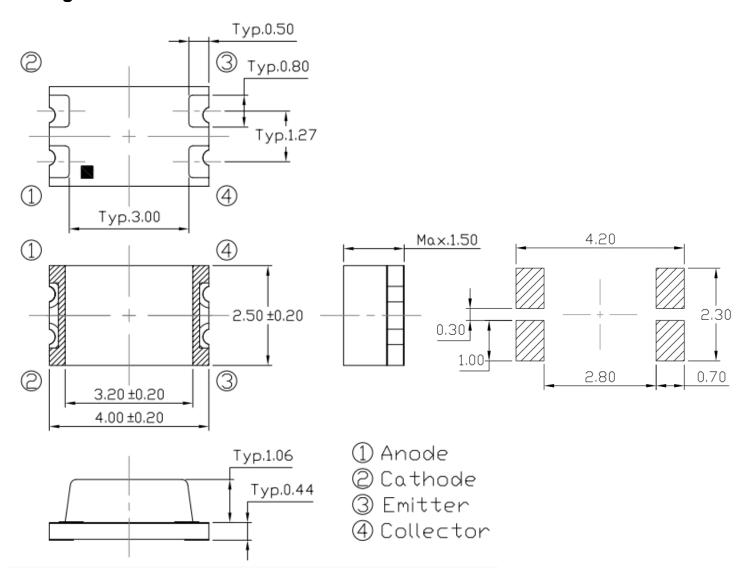
## **Test Circuit**



**Figure 14: Switching Time Test Circuits** 



### Package Dimension Dimensions in mm unless otherwise stated



## **Marking Information**



### Note:

• : Pin 1

CT : Denotes "CT Micro"

V : VDE Safety Mark Option (Blank or V)

17 : Part Number

Y : One Digit Year Code

X : CTR Rank

WW : Two Digit Work WeekK : Manufacturing Code



## **Ordering Information**

## CTP17X (V)(Z)

CT = Denotes "CT Micro"

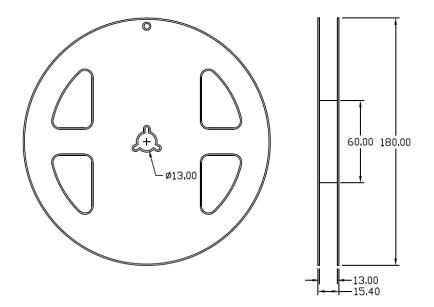
P17 = Part Numbers (X= 0,1,2,3,4,5,6,7,8,9)
X = CTR Rank Option (Blank or B, C, D)
V = VDE Safety Mark Option (Blank or V)

Z = Tape and Reel Option (T1 only)

Option	Description	Quantity
T1	Option 1 Taping	2500 Units/Reel

## Reel Dimension All dimensions are in mm, unless otherwise stated

## **Option T1**

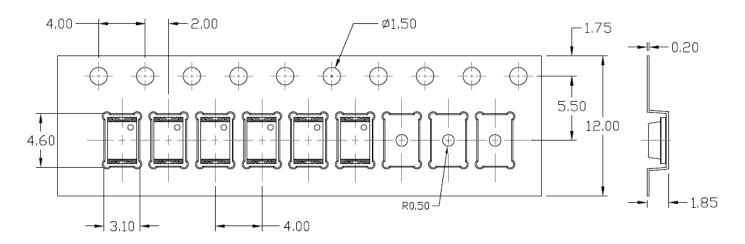




## Carrier Tape Specifications Dimensions in mm unless otherwise stated

### **Option T1**







### Solderability spec (follow the JEDEC standard JESD22-B102)

Reflow Soldering: Immersed surface, other than the end of pin as cut-surface, must be covered by solder.

Solder-Bath: More than 95% of the electrode must be covered with solder.

## **Wave soldering (follow the JEDEC standard JESD22-A111)**

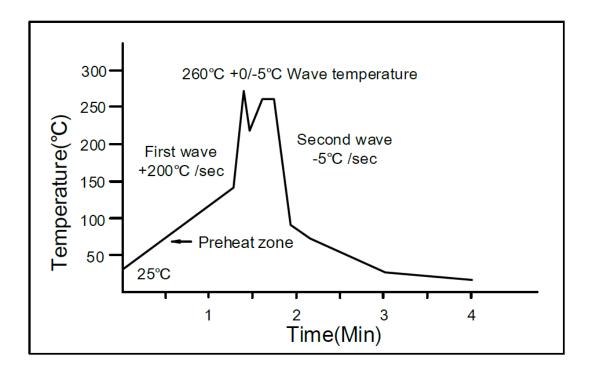
One time soldering is recommended within the condition of temperature.

Temperature: 260+0/-5°C.

Time: 10 sec.

Preheat temperature:25 to 140°C.

Preheat time: 30 to 80 sec.



## Iron soldering (follow the standard MIL-STD 202G, Method 210F)

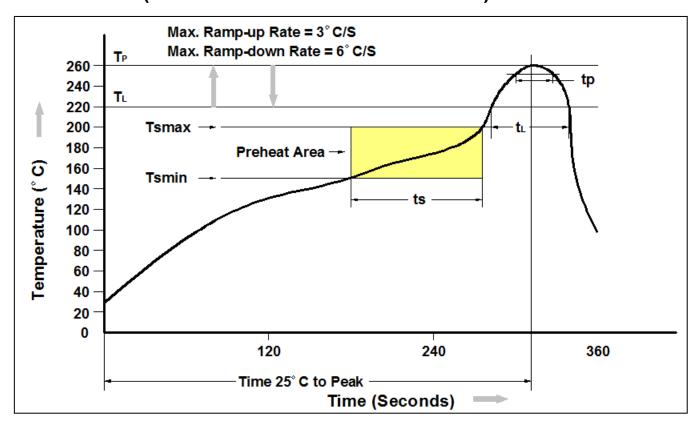
Allow single lead soldering in every single process.

One time soldering is recommended. Temperature: 350+±10°C

Time: 5 sec max.



## Reflow Profile (follow the JEDEC standard J-STD-020)



Profile Feature	Pb-Free Assembly Profile
Temperature Min. (Tsmin)	150°C
Temperature Max. (Tsmax)	200°C
Time (ts) from (Tsmin to Tsmax)	60-120 seconds
Ramp-up Rate (t∟ to t⊳)	3°C/second max.
Liquidous Temperature (T <sub>L</sub> )	217°C
Time (t <sub>L</sub> ) Maintained Above (T <sub>L</sub> )	60 – 150 seconds
Peak Body Package Temperature	260°C +0°C / -5°C
Time (t <sub>P</sub> ) within 5°C of 260°C	30 seconds
Ramp-down Rate (T <sub>P</sub> to T <sub>L</sub> )	6°C/second max
Time 25°C to Peak Temperature	8 minutes max.



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